

**WHAT IS CLAIMED IS:**

1       1. An apparatus for socketing and testing integrates  
2       circuits comprising:

3               an air machine; and

4               a housing comprising (i) a printed circuit board that  
5       is operable to receive a device under test, and (ii) a controller  
6       that is operable to control testing of the received device under  
7       test;

8               wherein said air machine is associable with said  
9       housing to form an at least substantially air-tight chamber  
10      ensconcing the received device under test.

1       2. The apparatus as set forth in Claim 1 wherein said  
2       housing further comprises a power supply.

1       3. The apparatus as set forth in Claim 1 wherein said  
2       printed circuit board is circular shaped.

1       4. The apparatus as set forth in Claim 3 wherein said  
2       housing further comprises I/O connectors that are placed  
3       circumferentially and symmetrically near the edge of the printed  
4       circuit board.

1       5. The apparatus as set forth in Claim 3 wherein said  
2       printed circuit board comprises a leadless socket.

1       6. The apparatus as set forth in Claim 5 wherein said  
2       leadless socket is operable to receive the device under test in  
3       the center of the Printed circuit board.

100-25832-322-24

1        7. A method of operating an apparatus for socketing and  
2 testing integrated circuits, said apparatus comprising an air  
3 machine and a housing, said housing comprising a printed circuit  
4 board and a controller, said method comprising the steps of  
5 (i) receiving a device under test, and (ii) associating said air  
6 machine with said housing to form an at least substantially air-  
7 tight chamber ensconcing the received device under test.

1        8. The method as set forth in Claim 7 wherein said housing  
2 further comprises a power supply, and said method comprising the  
3 step of powering on the apparatus.

1        9. The method as set forth in Claim 7 wherein said printed  
2 circuit board is circular shaped, and said method comprising the  
3 step of controlling testing of the received device under test  
4 with said controller.

1        10. The method as set forth in Claim 9 wherein said housing  
2 further comprises I/O connectors that are placed  
3 circumferentially and symmetrically near the edge of the printed  
4 circuit board.

1        11. The method as set forth in Claim 9 wherein said printed  
2 circuit board comprises a leadless socket.

1        12. The method as set forth in Claim 11 wherein said  
2           leadless socket is operable to receive the device under test in  
3           the center of the Printed circuit board.

1       13. An apparatus for socketing and testing integrated  
2       circuits comprising:

3                 an air machine; and

4                 a housing comprising (i) a universal printed circuit  
5       board that is operable to receive a device under test,(ii) a  
6       controller that is operable to control testing of the received  
7       device under test, and (ii) a power supply;

8                 wherein said air machine is associable with said  
9       housing to form an at least substantially air-tight chamber  
10      ensconcing the received device under test.

1       14. The apparatus as set forth in Claim 13 wherein said  
2       power supply is a battery.

1       15. The apparatus as set forth in Claim 13 wherein said  
2       universal printed circuit board is circular shaped.

1       16. The apparatus as set forth in Claim 15 wherein said  
2       housing further comprises I/O connectors that are placed  
3       circumferentially and symmetrically near the edge of the  
4       universal printed circuit board.

1       17. The apparatus as set forth in Claim 15 wherein said  
2       printed circuit board comprises a leadless socket.

1       18. The apparatus as set forth in Claim 17 wherein said  
2 leadless socket is operable to receive the device under test in  
3 the center of the printed circuit board.

1       19. The apparatus as set forth in Claim 13 wherein the  
2 device under test is one of a RF integrated circuit and a  
3 high-frequency integrated circuit.

1       20. The apparatus as set forth in Claim 17 wherein said  
2 leadless socket is self-registering.

330 330 330 330 330 330 330